

1 **ABSTRACT OF THE DISCLOSURE**

2 A method for fabricating high integration multi-layer DPC lines on a
3 ceramic board is to make the high density of multi-layer metal lines with
4 insulating layer and the fine through holes. The metal lines are able to form in the
5 different insulating layers, so as to the density of the metal lines is high. Besides
6 the through holes defined in the ceramic board are fine, so that the space where
7 the metal lines formed on is larger than the normal. Thus the fine through holes
8 are stuffed with the conductive material, so that the quantity of the inductor of the
9 metal lines is as possible as decreasing.